

Technical Datasheet

PXP® series is developed to withstand a broad range of processes. PXP® offers a superior balance between strong physical properties and withstanding aggressive chemical families including acids, amines, bases, aldehydes, ethylene oxide and hot water and steam. This material is produced in a dedicated clean room and provides the exceptional performance required in Semiconductor Industry.



Features and Benefits

- Low Compression Set
- Peroxide Curing System
- Exceptional Mechanical Properties
- Broad Chemical Resistance



Chemical Applications:

- Organic Acids
- Inorganic Acids
- Bases
- Amines
- Steam or Hot Water
- Ketones
- Aldehydes

Physical Properties

Color	Black	
PROPERTIES	ASTM	VALUE
Hardness, (Shore A)	D2240	80-/+5
Tensile Strength psi (MPa)	D1414	2749 (13.82)
Elongation, %, min	D1414	133
Modulus at 100% psi, (MPa), min	D1414	1513 (10.5)
Compression Set (70 Hrs @ 175°C (ASTM D395, Method B)	9.4	
Maximum Operating Temperature	280°C	

****EVEN THOUGH ELONGATION PROPERTY IS INDICATED, MOST PERFLUROELASTOMER MATERIALS SHOULD NOT BE STRETCHED FOR OPTIMAL PERFORMANCE.**

Note: color variations may be observed in parts. Variations are considered to be cosmetic and inherent as a result of curing process, not indicative for foreign matter and is not expected to have an adverse effect on the performance of the part in service.



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